

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	87	((photoinitiator with (weight percent\$5 "%")))) and (ic driver) near3 (bond\$5 attach\$5 connect\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:27
L2	0	((photoinitiator with (weight percent\$5 "%")))) same (ic driver) near3 (bond\$5 attach\$5 connect\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:28
L3	5	((photoinitiator with (weight percent\$5 "%")))) same (ic driver chip) near3 (bond\$5 attach\$5 connect\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:29
L4	15	((photoinitiator with (weight percent\$5 "%")))) same (ic driver chip microchip circuit\$5) near3 (bond\$5 attach\$5 connect\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:31
L5	155	((photoinitiator with (weight percent\$5 "%")))) and "349"/\$3.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:32
L6	0	((photoinitiator with (weight percent\$5 "%")))) and "349"/149-152.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:32
L7	65	((photoinitiator with (weight percent\$5 "%")))) and ((display panel) with (driver chip ic microchip))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:34
L8	7	((photoinitiator with (weight percent\$5 "%")))) same ((adhesiv\$5 bond attach\$5 connect\$5) with (chip driver microchip ic))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:43
L9	14	((photoinitiator with (weight percent\$5 "%")))) same ((adhesiv\$5 bond attach\$5 connect\$5) with (chip driver microchip ic circuit))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 18:02
L10	281	324/770.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 18:02
S1	193	349/192.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:40
S2	3078	349/54,55,149-152,187,192.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:41
S3	322	(attach\$5 bond\$5) near3 (driver chip ic tcp) with (before after) with (inspect\$5 repair\$5 correct\$5 defect\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:08

S4	6	S2 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:42
S5	55	(temporar\$5) near3 (bond\$5 attach\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:50
S6	0	S2 and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:47
S7	118	(temporar\$5) near3 (bond\$5 attach\$5 connect\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:08
S8	1	S2 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 09:50
S9	28	("4697885"   "4964700"   "4985663"). PN. OR ("5317438").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/05 10:04
S10	856	(attach\$5 bond\$5) near3 (driver chip ic tcp) with (before after) with (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:24
S11	426	(temporar\$5) near3 (bond\$5 attach\$5 connect\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:55
S12	1	S2 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:12
S13	8	S2 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:13
S14	2	S2 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:16
S15	3	"04062946"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 10:16
S16	1	1992-119750.NRAN.	DERWENT	OR	ON	2005/12/05 10:16
S17	1	1992-119750.NRAN.	DERWENT	OR	ON	2005/12/05 10:16

S18	16	(temporar\$5) near3 (bond\$5 attach\$5 connect\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5) and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 09:28
S19	16	((temporar\$5) near3 (bond\$5 attach\$5 connect\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5)) and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:50
S20	0	342/770.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:18
S21	287	324/770.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:18
S22	42	(attach\$5 bond\$5) near3 (driver chip ic tcp) with (before after prior) with (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5) and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:20
S23	3	S10 and S21	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:27
S24	0	S11 and S21	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:27
S25	8677	438/12,14-18,118,119.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:27
S26	266	438/12,14-18,118,119.ccls. and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:28
S27	2	S11 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:29
S28	51	S11 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:29
S29	7	S11 and S25 and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:31

S30	3	"04062946"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:47
S31	2	("5317438").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/05 11:47
S32	37837	((temporar\$5) near3 (bond\$5 attach\$5 connect\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:51
S33	247	S25 and S32	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:51
S34	5	S25 and S32 and (photoinitiator (photo adj initiator))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 11:54
S35	18	S25 and S32 and (polymer near5 adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 12:37
S36	0	S25 and S32 and (polymer near5 adhesive) same (therm\$5 heat\$5) same (uv ultraviolet light\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 12:38
S37	1003	(polymer near5 adhesive) same (therm\$5 heat\$5) same (uv ultraviolet light\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 13:21
S38	30	((polymer near5 adhesive) same (therm\$5 heat\$5) same (uv ultraviolet light\$5)) and S32	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/05 13:21
S39	16	(tempora\$5) near3 (bond\$5 attach\$5 connect\$5) with ((driv\$5 adj circuit) driver ic chip) same (inspect\$5 repair\$5 correct\$5 defect\$5 test\$5) and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:03
S40	2	((photo adj initiator) photoinitiator) with ((photosensitive (photo adj sensitive) uv ultraviolet) adj adhesive) with polymer\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:07
S41	14	((photo adj initiator) photoinitiator) with ((photosensitive (photo adj sensitive) uv ultraviolet) adj adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:07

S42	123	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 (heat near cur\$5)) with (uv light radiat\$5 ultraviolet))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:28
S43	3	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5) with tempor\$5) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 (heat near cur\$5)) with (uv light radiat\$5 ultraviolet))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:33
S44	7	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 (heat near cur\$5)) with (uv light radiat\$5 ultraviolet)) and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:39
S45	123	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 (heat near cur\$5)) with (uv light radiat\$5 ultraviolet))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 12:09
S46	28	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 (heat near5 cur\$5)) same (uv light radiat\$5 ultraviolet)) and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 10:53
S47	41	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with (thermoset\$5 ((heat\$5 therm\$5) near5 cur\$5)) same (uv light radiat\$5 ultraviolet)) and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 11:03
S48	2	"04177477"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 11:03
S49	48	("4242157"   "4717605"   "4811081"). PN. OR ("5261156").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 12:03
S50	97	polymer\$5 with adhesiv\$5 with photoinitiator same (weight percent\$5 "%")	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 12:03
S51	14	polymer\$5 with adhesiv\$5 with photoinitiator same (weight percent\$5 "%") and display	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 12:07
S52	13	((polymer\$5 with adhesiv\$5) same (photoinitiator with (weight percent\$5 "%")))) and display	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 17:26

S53	1279	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with polymer\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 12:10
S54	45	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with polymer\$5) and display.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 12:18
S55	2	("5261156").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/06 12:13
S56	22	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with polymer\$5).ti,ab,clm. and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 12:24
S57	6	((ic driver driv\$5 adj (circuit chip) chip microchip) with (bond\$5 connect\$5 attach\$5)) same ((adhesiv\$5 epoxy\$5) with polymer\$5 with photoinitiator)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 12:29
S58	2	("5366573").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/06 12:29
S59	3	"04117477"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 13:20
S60	1	1992-180214.NRAN.	DERWENT	OR	ON	2005/12/06 13:19
S61	501	(koji near matsui).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 13:20
S62	42	(koji near matsui).in. and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 13:21
S63	2	(koji near matsui).in. and adhesive and display	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 13:25
S64	9	photothermosetting	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/06 13:44
S65	2	("5317438").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/08 14:16

S66	2	("5858806").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/08 14:16
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